



SOLDERING FOOTPRINT* 5.30 3.30 -0.78 3.30 5.30 PACKAGE OUTLINE 20X

RECOMMENDED

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

0.40 DIMENSIONS: MILLIMETERS

PITCH

DATE 02 APR 2013

NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.25 AND 0.30 MM FROM THE TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- 5. OPTIONAL FEATURES.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1		0.05	
A3	0.20 REF		
b	0.25	0.35	
D	5.00 BSC		
D2	3.05	3.25	
E	5.00 BSC		
E2	3.05	3.25	
е	0.65 BSC		
L	0.45	0.65	
L1		0.15	

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location Α

WL = Wafer Lot YY = Year = Work Week ww = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	QFN20 5x5, 0.65P		PAGE 1 OF 1

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